TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

2SK2838

Chopper Regulator, DC-DC Converter and Motor Drive Applications

• Low drain—source ON resistance : RDS (ON) = 0.84Ω (typ.) • High forward transfer admittance : $|Y_{fs}| = 4.4 S$ (typ.) • Low leakage current : IDSS = $100 \mu A$ (max) (VDS = 400 V) • Enhancement—mode : $V_{th} = 2.0 \sim 4.0 V$ (VDS = 10 V, ID = 1 mA)

Maximum Ratings (Ta = 25°C)

Characteri	stics	Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	400	V
Drain-gate voltage (R	_{GS} = 20 kΩ)	V_{DGR}	400	V
Gate-source voltage		V_{GSS}	±30	V
Drain current	DC (Note 1)	I_{D}	5.5	Α
	Pulse (Note 1)	I_{DP}	22	Α
Drain power dissipatio	n (Tc = 25°C)	P_{D}	40	W
Single pulse avalanche	e energy (Note 2)	E _{AS}	223	mJ
Avalanche current		I _{AR}	5.5	Α
Repetitive avalanche	energy (Note 3)	E _{AR}	4.0	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature r	ange	T _{stg}	-55~150	°C

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	3.125	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	83.3	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

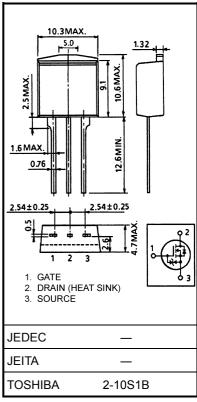
Note 2: $V_{DD} = 90 \text{ V}$, $T_{ch} = 25^{\circ}\text{C}$ (initial), L = 12.0 mH, $R_G = 25 \Omega$, $I_{AR} = 5.5 \text{ A}$

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

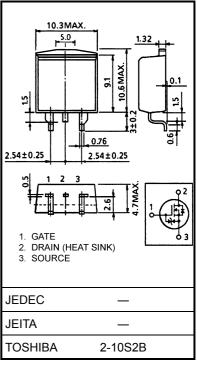
This transistor is an electrostatic sensitive device.

Please handle with caution.

Unit: mm



Weight: 1.5 g (typ.)



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Electrical Characteristics (Ta = 25°C)

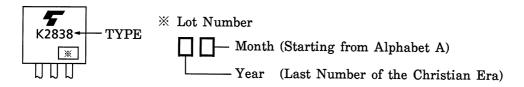
Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V (BR) GSS	$I_G = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 400 V, V _{GS} = 0 V	-	_	100	μΑ
Drain-source br	eakdown voltage	V _{(BR) DSS}	I _D = 10 mA, V _{GS} = 0 V	400	_	_	V
Gate threshold v	voltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 3 A	_	0.84	1.2	Ω
Forward transfer	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 3 A	2.0	4.4	_	S
Input capacitano	e	C _{iss}		_	720	_	
Reverse transfer capacitance C_{rss} V_{DS} = 10 V, V_{GS} = 0 V,		V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	80	_	pF	
Output capacitance		C _{oss}]	_	250	_	
Switching time	Rise time	t _r	V_{GS} V_{OV} V_{OUT} V_{OUT} V_{DD} V_{DD}	_	15	_	
	Turn-on time	t _{on}		_	30	_	ne
	Fall time	t _f		_	25	_	ns
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\mathbf{W}} = 10 \mu \text{s}$	_	110	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	17	_	
Gate-source charge		Q _{gs}	V _{DD} =320 V, V _{GS} = 10 V, I _D = 5.5 A		10		nC
Gate-drain ("miller") Charge		Q _{gd}			7		

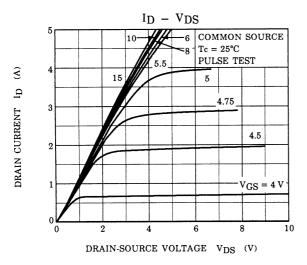
Source-Drain Ratings and Characteristics (Ta =

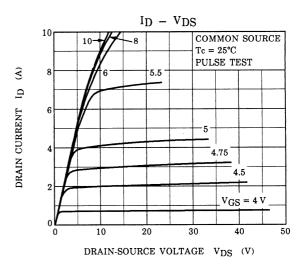
25°C)

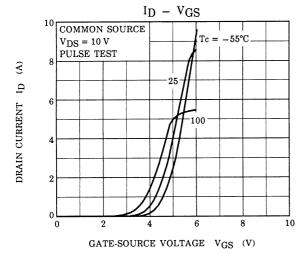
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	5.5	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	22	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 5.5 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 5.5 A, V _{GS} = 0 V	_	350	_	ns
Reverse recovery charge	Q _{rr}	dI _{DR} / dt = 100 Å / μs	_	2.1	_	μC

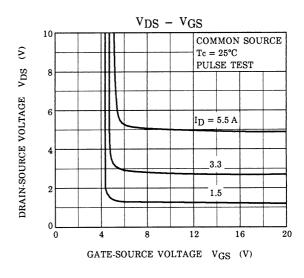
Marking

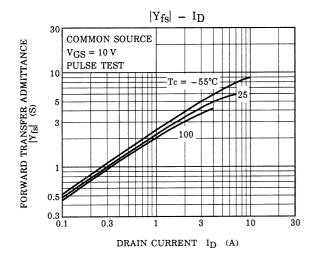


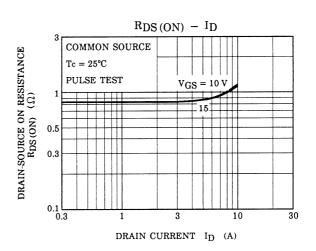




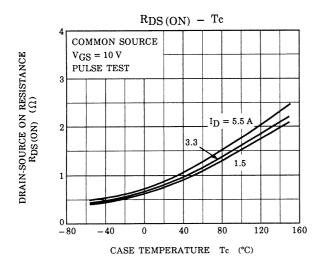


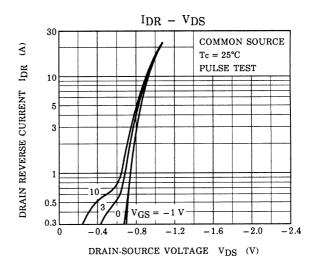


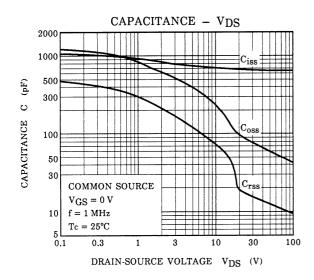


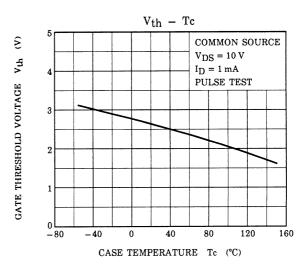


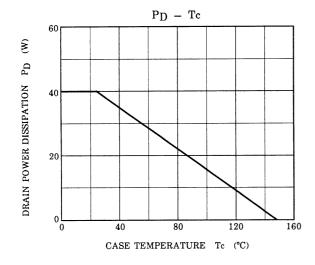
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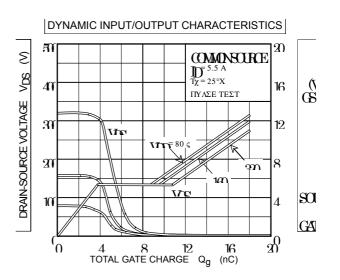




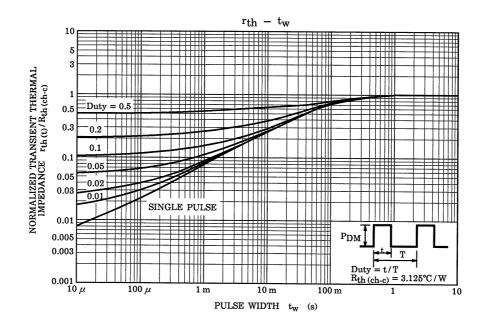


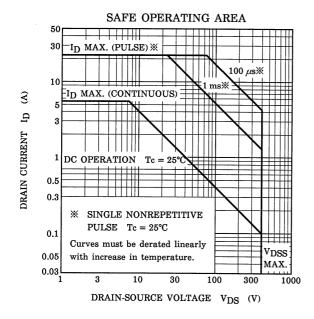


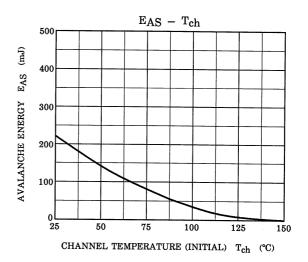


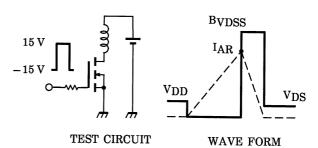


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$$\begin{aligned} &R_G = 25~\Omega \\ &V_{DD} = 90~V,~L = 12~mH \end{aligned} \qquad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BV_{DSS}}{BV_{DSS} - V_{DD}} \right)$$

RESTRICTIONS ON PRODUCT USE

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